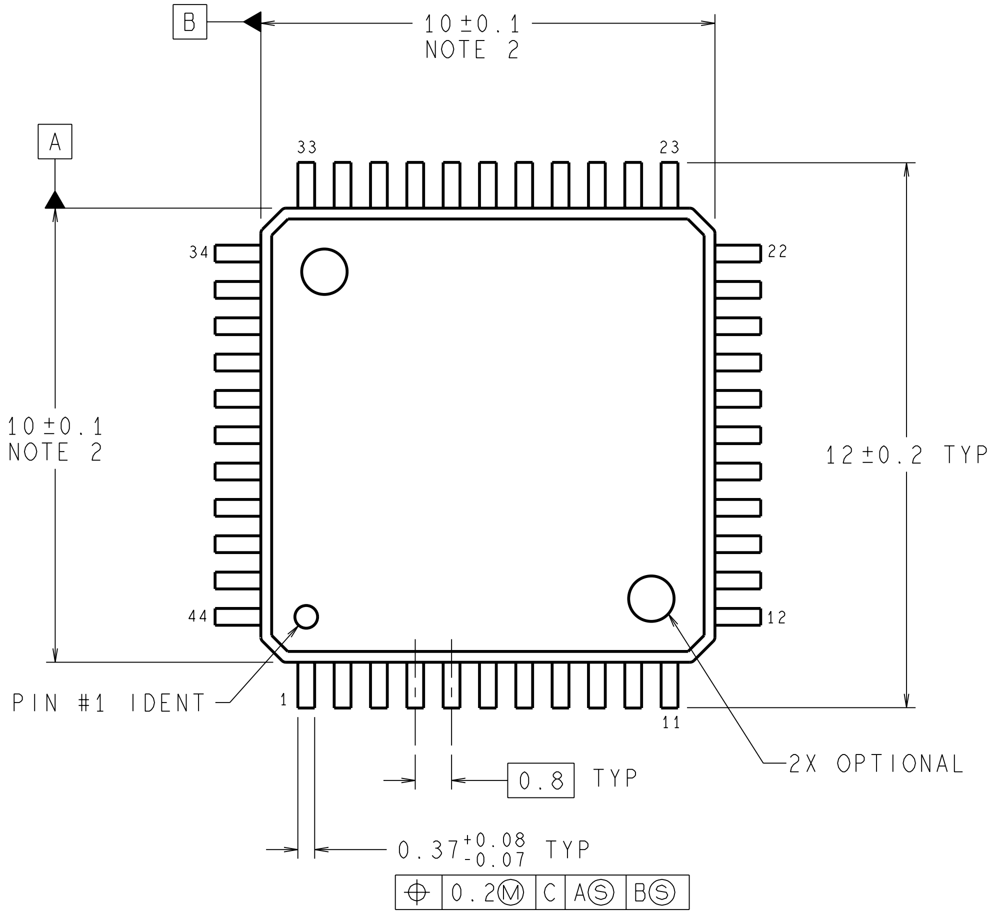
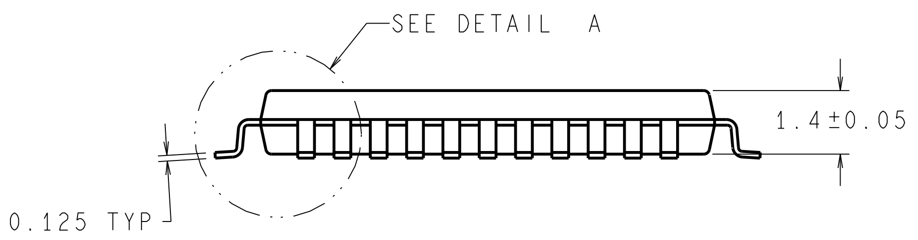
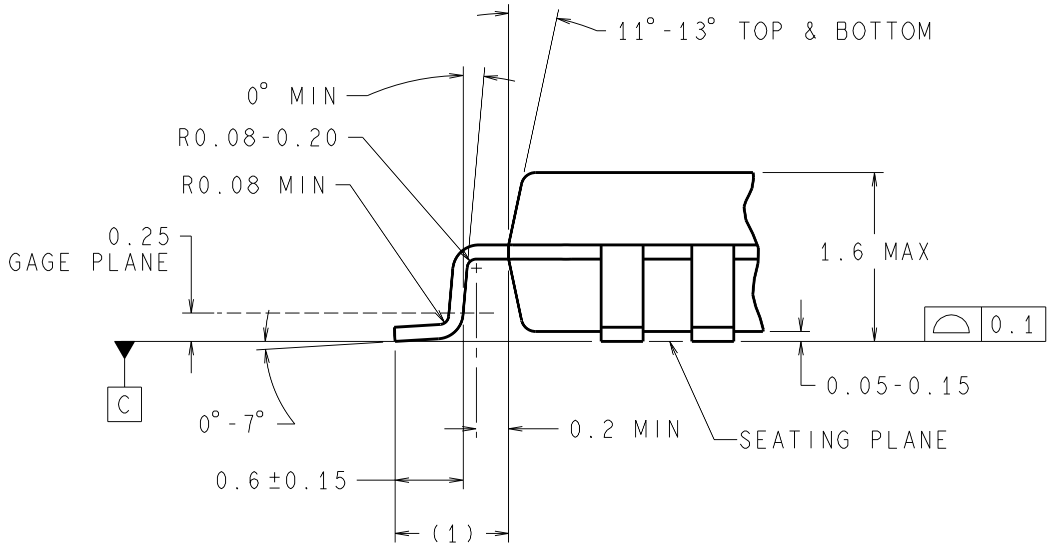
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10189	01/25/1994	DEG/HJK
B	TITLE: LQFP WAS PQFP;UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE	12317	12/02/1999	ACS/MS/RW







DETAIL A
TYP,SCALE:25X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
   7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
   THICKNESS ON COPPER.
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MS-026, VARIATION BCB,
   DATED FEB 1999.

APPROVALS	DATE
DRAWN D.E.GRADY	01/25/1994
DFTG. CHK. THANH LEQUANG	12/07/1999
ENGR. CHK. RANDALL WALBERG	12/07/1999

PROJECTION
INCH
[MM]

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LQFP, JEDEC METRIC, 10 X 10 X 1.4mm, 44 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-VEJ44A	B

FORMERLY:
SHEET 1 of 1